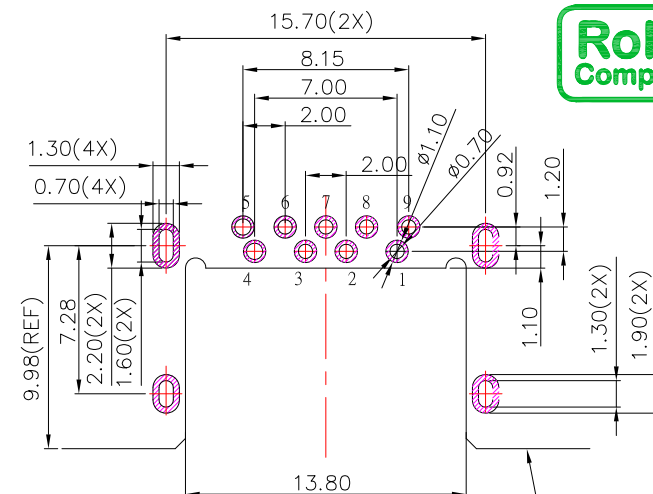
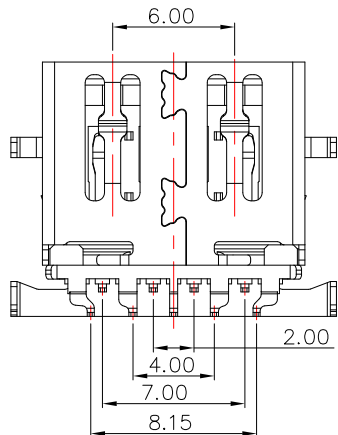
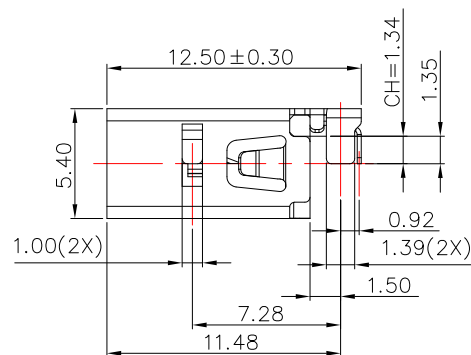
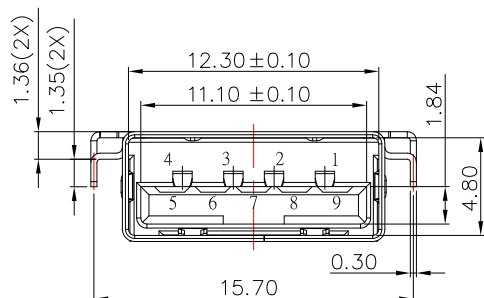
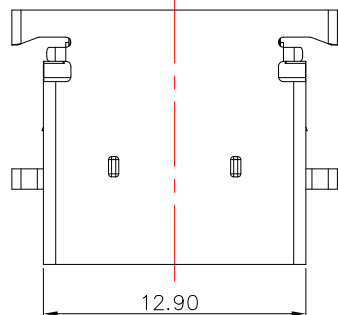




# SUA-110E7-30xx-S277

鍍層厚度 : HOUSING :

Blank : 1u"	Blank : Blue
2 : 15u"	K : BLack
3 : 30u"	



RECOMMENDED PCB LAYOUT  
TOP VIEW

PCB EDGE

NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: Copper Alloy
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Rate: 30V DC , 1.8 A(VBUS & GND);0.25 A(other pin);
- 3.2 Insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -25°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N

USB 3.0 PIN ASSIGNMENTS

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST



TOLERANCE UNLESS OTHERWISE STATED :

Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3°

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/19/20		MODLE	USB AF 3.0 DIP 沉板, 板上H:1.36mm L:12.5, 無捲邊反向
CHECKED BY:	DATE	FINISH	DWG NO.	SUA-110E7-30xx-S277
Jacky Chen	06/19/20		SHEET NO.	1 of 1
APPROVED BY:	DATE	SCALE	PART NO.	SUA-110E7-30xx-S277
Tony Kao	06/19/20	1 : 1		

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新圖面	Jack	06/19/20